

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TDA21240	**Issued**	16. October 2019
MA#	MA001650100		
Package	PG-IQFN-30-2	**Weight***	55.72 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.569	1.02	1.02	10215	10215
chip_2	inorganic material	silicon	7440-21-3	0.192	0.34	0.34	3450	3450
chip_3	inorganic material	silicon	7440-21-3	0.543	0.97	0.97	9746	9746
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		83	
	non noble metal	zinc	7440-66-6	0.018	0.03		331	
	non noble metal	iron	7439-89-6	0.368	0.66		6610	
	non noble metal	copper	7440-50-8	14.956	26.84	27.54	268410	275434
wire	non noble metal	copper	7440-50-8	0.085	0.15	0.15	1518	1518
encapsulation	organic material	carbon black	1333-86-4	0.047	0.08		834	
	plastics	epoxy resin	-	2.395	4.30		42977	
	inorganic material	silicondioxide	60676-86-0	20.809	37.36	41.74	373439	417250
leadfinish	non noble metal	tin	7440-31-5	0.593	1.06	1.06	10638	10638
plating	noble metal	silver	7440-22-4	0.040	0.07	0.07	721	721
solder	noble metal	silver	7440-22-4	0.021	0.04		369	
	non noble metal	tin	7440-31-5	0.041	0.07		738	
	non noble metal	lead	7439-92-1	0.761	1.37	1.48	13661	14768
glue	plastics	epoxy resin	-	0.088	0.16		1586	
	noble metal	silver	7440-22-4	0.265	0.48	0.64	4758	6344
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003	0.01		61	
	non noble metal	zinc	7440-66-6	0.014	0.02		245	
	non noble metal	iron	7439-89-6	0.273	0.49		4892	
	non noble metal	copper	7440-50-8	11.069	19.86	20.38	198642	203840
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		14	
	non noble metal	zinc	7440-66-6	0.003	0.01		55	
	non noble metal	iron	7439-89-6	0.062	0.11		1106	
	non noble metal	copper	7440-50-8	2.502	4.49	4.61	44901	46076
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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